## Switching Diode

## BAS16L

## Features

- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are $\mathrm{Pb}-$ Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
| :--- | :---: | :---: | :---: |
| Continuous Reverse Voltage | $\mathrm{V}_{\mathrm{R}}$ | 100 | V |
| Peak Forward Current | $\mathrm{I}_{\mathrm{F}}$ | 200 | mA |
| Non-Repetitive Peak Forward Surge <br> Current 60 Hz | $\mathrm{I}_{\text {FSM(surge) }}$ | 1.8 | A |
| Repetitive Peak Forward Current | $\mathrm{I}_{\text {FRM }}$ | 1.0 | A |
| (Note 3) |  |  |  |
| Non-Repetitive Peak Forward Current | $\mathrm{I}_{\text {FSM }}$ |  | A |
| (Square Wave, $\mathrm{T}_{J}=25^{\circ} \mathrm{C}$ prior to |  |  |  |
| surge) |  | 36.0 |  |
| $\mathrm{t}=1 \mu \mathrm{~s}$ |  | 18.0 |  |
| $\mathrm{t}=10 \mu \mathrm{~S}$ |  | 6.0 |  |
| $\mathrm{t}=100 \mu \mathrm{~S}$ | $\mathrm{t}=1 \mathrm{~ms}$ | 1.0 |  |
| $\mathrm{t}=10 \mathrm{~ms}$ |  |  |  |
| $\mathrm{t}=100 \mathrm{~ms}$ |  | 1.3 |  |
| $\mathrm{t}=1 \mathrm{~s}$ |  | 1.0 |  |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
THERMAL CHARACTERISTICS

| Characteristic | Symbol | Max | Unit |
| :--- | :---: | :---: | :---: |
| Total Device Dissipation FR-5 Board <br> (Note 1) <br> $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ <br> Derate above $25^{\circ} \mathrm{C}$ | $\mathrm{P}_{\mathrm{D}}$ | 225 | mW |
| Thermal Resistance, <br> Junction-to-Ambient | $\mathrm{R}_{\text {日JA }}$ | 556 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| Total Device Dissipation <br> Alumina Substrate, (Note 2) <br> $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ <br> Derate above $25^{\circ} \mathrm{C}$ | $\mathrm{P}_{\mathrm{D}}$ | 300 | mW |
| Thermal Resistance, <br> Junction-to-Ambient | $\mathrm{R}_{\text {日JA }}$ | 417 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| Junction and Storage Temperature | $\mathrm{T}_{\mathrm{J},}, \mathrm{T}_{\mathrm{stg}}$ | -55 to +150 | ${ }^{\circ} \mathrm{C}$ |

1. $\mathrm{FR}-5=1.0 \times 0.75 \times 0.062 \mathrm{in}$.
2. Alumina $=0.4 \times 0.3 \times 0.024 \mathrm{in} .99 .5 \%$ alumina.
3. Square Wave, $\mathrm{f}=40 \mathrm{kHz}, \mathrm{PW}=200 \mathrm{~ns}$

Test Duration $=60 \mathrm{~s}, \mathrm{~T}_{\mathrm{J}}=25^{\circ} \mathrm{C}$ prior to surge.


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SOT-23
CASE 318
STYLE 8


A6 = Specific Device Code
M = Date Code*

- = Pb-Free Package
(Note: Microdot may be in either location)
*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

| Device | Package | Shipping ${ }^{\dagger}$ |
| :---: | :---: | :---: |
| BAS16LT1G | SOT-23 <br> (Pb-Free) | 3000/Tape \& Reel |
| BAS16LT3G | SOT-23 <br> (Pb-Free) | 10000/Tape \& Reel |
| SBAS16LT1G | SOT-23 <br> (Pb-Free) | 3000/Tape \& Reel |
| SBAS16LT3G | SOT-23 <br> (Pb-Free) | 10000/Tape \& Reel |

$\dagger$ For information on tape and reel specifications,
including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS $\left(T_{A}=25^{\circ} \mathrm{C}\right.$ unless otherwise noted)

| Characteristic | Symbol | Min | Max | Unit |
| :---: | :---: | :---: | :---: | :---: |

OFF CHARACTERISTICS

| Reverse Voltage Leakage Current $\begin{aligned} & \left(V_{R}=100 \mathrm{~V}\right) \\ & \left(\mathrm{V}_{\mathrm{R}}=75 \mathrm{Vdc}, \mathrm{~T}_{J}=150^{\circ} \mathrm{C}\right) \\ & \left(\mathrm{V}_{\mathrm{R}}=25 \mathrm{Vdc}, \mathrm{~T}_{J}=150^{\circ} \mathrm{C}\right) \end{aligned}$ | $\mathrm{I}_{\mathrm{R}}$ |  | $\begin{aligned} & 1.0 \\ & 50 \\ & 30 \end{aligned}$ | $\mu \mathrm{Adc}$ |
| :---: | :---: | :---: | :---: | :---: |
| Reverse Breakdown Voltage $\left(l_{\mathrm{BR}}=100 \mu \mathrm{Adc}\right)$ | $\mathrm{V}_{\text {(BR) }}$ | 100 | - | Vdc |
| $\begin{gathered} \text { Forward Voltage } \\ \left(I_{F}=1.0 \mathrm{mAdc}\right) \\ \left(I_{F}=10 \mathrm{mAdc}\right) \\ \left(I_{F}=50 \mathrm{mAdc}\right) \\ \left(I_{F}=150 \mathrm{mAdc}\right) \end{gathered}$ | $\mathrm{V}_{\mathrm{F}}$ |  | $\begin{gathered} 715 \\ 855 \\ 1000 \\ 1250 \end{gathered}$ | mV |
| Diode Capacitance $\left(\mathrm{V}_{\mathrm{R}}=0, \mathrm{f}=1.0 \mathrm{MHz}\right)$ | $\mathrm{C}_{\mathrm{D}}$ | - | 2.0 | pF |
| Forward Recovery Voltage ( $\mathrm{I}_{\mathrm{F}}=10 \mathrm{mAdc}, \mathrm{t}_{\mathrm{r}}=20 \mathrm{~ns}$ ) | $\mathrm{V}_{\text {FR }}$ | - | 1.75 | Vdc |
| Reverse Recovery Time $\left(\mathrm{I}_{\mathrm{F}}=\mathrm{I}_{\mathrm{R}}=10 \mathrm{mAdc}, \mathrm{R}_{\mathrm{L}}=50 \Omega\right)$ | $\mathrm{t}_{\mathrm{rr}}$ | - | 6.0 | ns |
| Stored Charge $\left(\mathrm{I}_{\mathrm{F}}=10 \mathrm{mAdc}\right.$ to $\mathrm{V}_{\mathrm{R}}=5.0 \mathrm{Vdc}, \mathrm{R}_{\mathrm{L}}=500 \Omega$ ) | $Q_{S}$ | - | 45 | pC |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.


Notes: 1. A $2.0 \mathrm{k} \Omega$ variable resistor adjusted for a Forward Current $\left(\mathrm{I}_{\mathrm{F}}\right)$ of 10 mA .
2. Input pulse is adjusted so $\mathrm{I}_{\mathrm{R} \text { (peak) }}$ is equal to 10 mA .
3. $t_{p}>t_{r r}$

Figure 1. Recovery Time Equivalent Test Circuit

## BAS16L

TYPICAL CHARACTERISTICS


Figure 2. $\mathbf{V}_{\mathrm{F}}$ vs. $\mathrm{I}_{\mathrm{F}}$


Figure 4. Capacitance


Figure 3. $\mathrm{I}_{\mathrm{R}}$ vs. $\mathrm{V}_{\mathrm{R}}$


Figure 5. Maximum Non-repetitive Peak Forward Current as a Function of Pulse Duration, Typical Values


SOT-23 (TO-236)
CASE 318-08
ISSUE AS
DATE 30 JAN 2018

## SCALE 4:1



NOTES:
IMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994
. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

|  | MILLIMETERS |  |  | INCHES |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| DIM | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 0.89 | 1.00 | 1.11 | 0.035 | 0.039 | 0.044 |
| A1 | 0.01 | 0.06 | 0.10 | 0.000 | 0.002 | 0.004 |
| b | 0.37 | 0.44 | 0.50 | 0.015 | 0.017 | 0.020 |
| $\mathbf{c}$ | 0.08 | 0.14 | 0.20 | 0.003 | 0.006 | 0.008 |
| D | 2.80 | 2.90 | 3.04 | 0.110 | 0.114 | 0.120 |
| E | 1.20 | 1.30 | 1.40 | 0.047 | 0.051 | 0.055 |
| e | 1.78 | 1.90 | 2.04 | 0.070 | 0.075 | 0.080 |
| L | 0.30 | 0.43 | 0.55 | 0.012 | 0.017 | 0.022 |
| L1 | 0.35 | 0.54 | 0.69 | 0.014 | 0.021 | 0.027 |
| $\mathbf{H E}_{\mathbf{E}}$ | 2.10 | 2.40 | 2.64 | 0.083 | 0.094 | 0.104 |
| T | $0^{\circ}$ | --- | $10^{\circ}$ | $0^{\circ}$ | --- | $10^{\circ}$ |

GENERIC
MARKING DIAGRAM*

RECOMMENDED SOLDERING FOOTPRINT


DIMENSIONS: MILLIMETERS


XXX = Specific Device Code
M = Date Code

- = Pb-Free Package
*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " $\quad$ ", may or may not be present.


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